



ALLIANCE MEMORY MDS REPORT

Part Number:			AS5F34G04SND-08LIN					
Part Weight:			896mg					
No.	Part Name	Component wt (mg)	Material Content(Element)	CAS Number	Homogeneous materialt wt(%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	27.276	Cu Foil	7440-50-8	15.000%	4.0914	0.4566%	150000
			Thermosetting resin (including filler)	Trade seacret	10.000%	2.7276	0.3044%	100000
			Glass cloth	65997-17-3	10.000%	2.7276	0.3044%	100000
			Acrylate Resin	Trade secret	7.000%	1.90932	0.2131%	70000
			3-Methoxy-3-methylbutylAcetate	103429-90-9	6.000%	1.63656	0.1827%	60000
			Barium Sulfate	7727-43-7	4.000%	1.09104	0.1218%	40000
			Naphtha (petroleum), heavy aromatic	64742-94-5	0.400%	0.109104	0.0122%	4000
			Photoinitiator	Trade secret	0.400%	0.109104	0.0122%	4000
			Propanol, 1(or 2)-(2-methoxymethylethoxy)-	34590-94-8	0.400%	0.109104	0.0122%	4000
			TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6	0.200%	0.054552	0.0061%	2000
			Aluminiumhydroxide	Trade secret	0.200%	0.054552	0.0061%	2000
			Amine compound	Trade secret	0.200%	0.054552	0.0061%	2000
			Benzene, 1,2,4-trimethyl	Trade secret	0.200%	0.054552	0.0061%	2000
			Benzene, trimethyl	Trade secret	0.200%	0.054552	0.0061%	2000
			Ethanol, 2-(2-ethoxyethoxy)-, 1-acetate	112-15-2	0.200%	0.054552	0.0061%	2000
			Naphthalene	91-20-3	0.200%	0.054552	0.0061%	2000
			Organic yellow pigment	Trade secret	0.200%	0.054552	0.0061%	2000
			Phthalocyanine Blue pigment	Trade secret	0.100%	0.027276	0.0030%	1000
			Precipitated Silica	112926-00-8	0.100%	0.027276	0.0030%	1000
			Copper	7440-50-8	30.000%	8.1828	0.9133%	300000
			Au Plating	7440-57-5	5.000%	1.3638	0.1522%	50000
			Ni Plating	7440-02-0	10.000%	2.7276	0.3044%	100000
2	Mold compound	56.835	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'-divl)bis(oxymethylene))-bis-oxirane	85954-11-6	8.000%	4.54680	0.5075%	80000
			Phenol Resin A	Trade Secret	2.700%	1.53455	0.1713%	27000
			Phenol Resin B	Trade Secret	2.800%	1.59138	0.1776%	28000
			Silica(Amorphous) A	60676-86-0	70.000%	39.78450	4.4402%	700000
			Silica(Amorphous) B	7631-86-9	8.000%	4.54680	0.5075%	80000
			Metal Hydroxide	Trade Secret	8.000%	4.54680	0.5075%	80000
			Carbon Black	1333-86-4	0.500%	0.28418	0.0317%	5000
3	Epoxy	2.495	Acrylic resin	Trade Secret	50.000%	1.24750	0.1392%	500000
			Silica, amorphous	7631-86-9	45.000%	1.12275	0.1253%	450000
			Phenol resin	Trade Secret	5.000%	0.12475	0.0139%	50000
4	Solder past	0.609	Tin	7440-31-5	96.500%	0.58769	0.0656%	965000
			Silver	7440-22-4	3.000%	0.01827	0.0020%	30000
			Copper	7440-50-8	0.500%	0.00305	0.0003%	5000
5	Gold wire	2.365	Gold	7440-57-5	99.996%	2.36491	0.2639%	999960
6	Controllor	25.373	Other	Trade Secret	0.004%	0.00009	0.0000%	40
7	Flash	267.066	Silicon	7440-21-3	100.000%	25.37300	2.8318%	1000000
8	Spacer	513.575	Aluminum	7429-90-5	98.000%	261.72468	29.2103%	980000
9	Component	0.406	Silicon	7440-21-3	2.000%	5.34132	0.5961%	20000
			Barium oxide, obtained by calcining witherite	1304-28-5	100.000%	513.57500	57.3186%	1000000
			Titanium dioxide	13463-67-7	32.513%	0.13200	0.0147%	325123
			Misc	Trade seacret	16.256%	0.06600	0.0074%	162562
			Copper	7440-50-8	5.419%	0.02200	0.0025%	54187
			diboron trioxide; boric oxide	7440-50-8	18.719%	0.07600	0.0085%	187192
			Silicon dioxide	1303-86-2	3.744%	0.01520	0.0017%	37438
			Nickel	7631-86-9	14.975%	0.06080	0.0068%	149754
			Nickel	7440-02-0	1.724%	0.00700	0.0008%	17241
Nickel	7440-02-0	1.970%	0.00800	0.0009%	19704			
Tin	7440-31-5	4.680%	0.01900	0.0021%	46798			
896			900.000%					
			896.0000					
			100.0000%					
			9000000					